

Appl. No. 10/711,392
Amtd. dated June 12, 2005
Reply to Office action of April 12, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) A chemical mechanical polishing process comprising:
 - 5 providing a substrate having thereon a top bulk metal layer and a lower barrier layer; polishing said top bulk metal layer at a substantial constant removal rate to expose said barrier layer by utilizing a first platen and a first slurry being selective to said barrier layer; and polishing said exposed barrier layer by using a second platen and a second slurry.
- 10 2. (Original) The chemical mechanical polishing process according to claim 1 wherein said first slurry has a copper to barrier polishing selectivity of greater than 30.
- 15 3. (Original) The chemical mechanical polishing process according to claim 2 wherein said first slurry has a copper to barrier polishing selectivity of above 100.
4. (Original) The chemical mechanical polishing process according to claim 1 wherein said first slurry contains alumina.
- 20 5. (Original) The chemical mechanical polishing process according to claim 1 wherein said second slurry contains alumina.
6. (Original) The chemical mechanical polishing process according to claim 1 wherein said first slurry contains silica.
- 25 7. (Original) The chemical mechanical polishing process according to claim 1 wherein said second slurry contains silica.